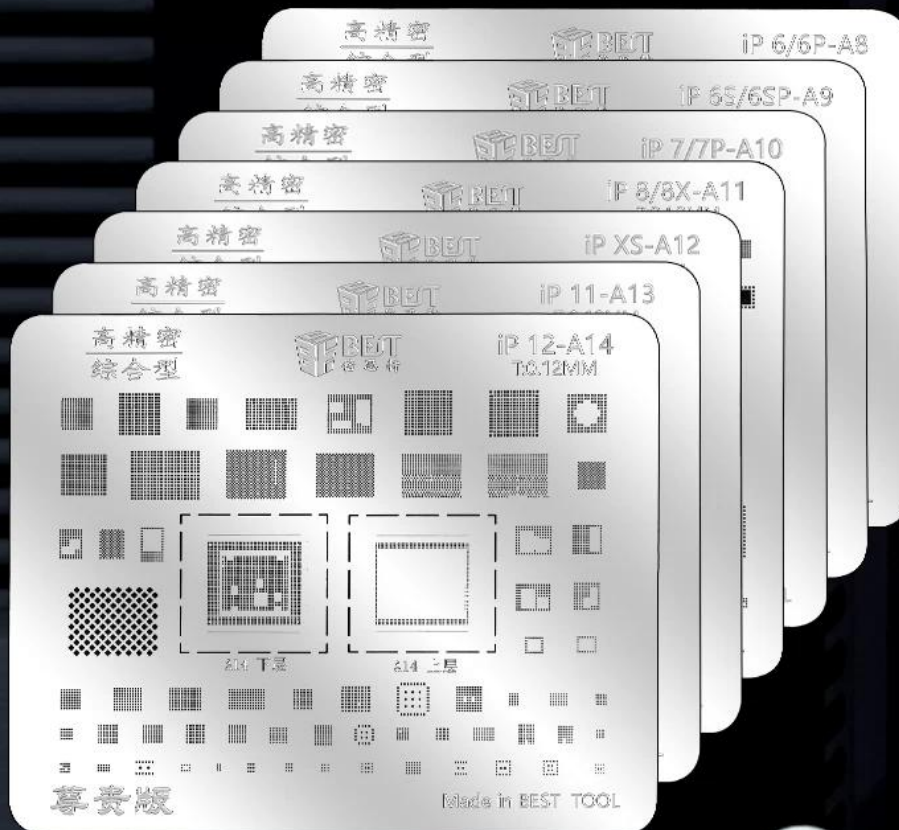


BGA IC

SOLDERING REBALLING STENCIL

High toughness

Strong magnetic steel



Product Usage



Model NO.	BST-iP (A8-A14)	Melting point	700℃
Name	Reballing Stencil	G.W.	25.8g
Material	Strong magnetic steel	Size	141*103*13.1mm





Four characteristics



Semi-etching process



Cooling hole design

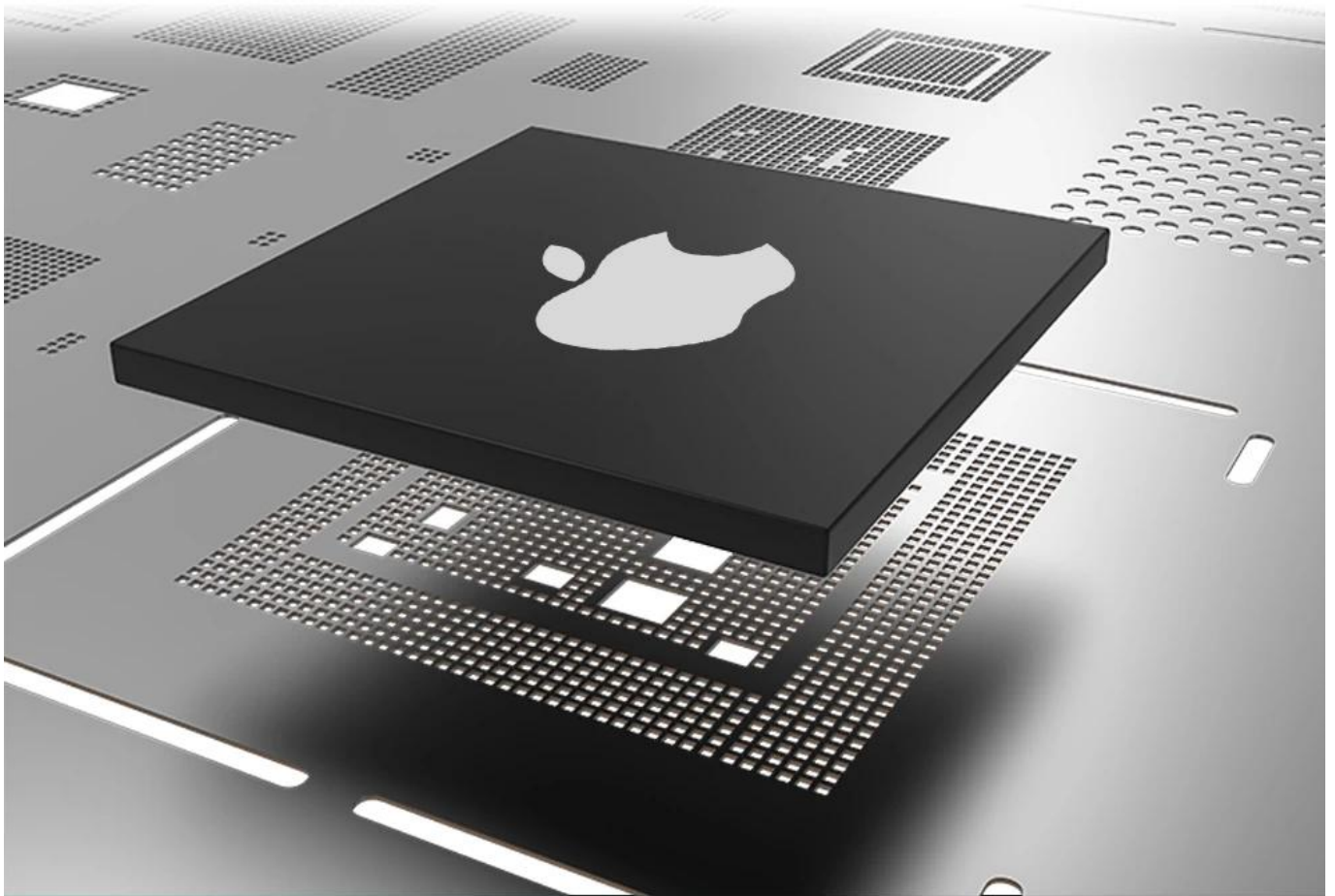


Square hole



Precise alignment

Easily mounted on the steel mesh to make the chip fit
more closely with the mesh Therefore.

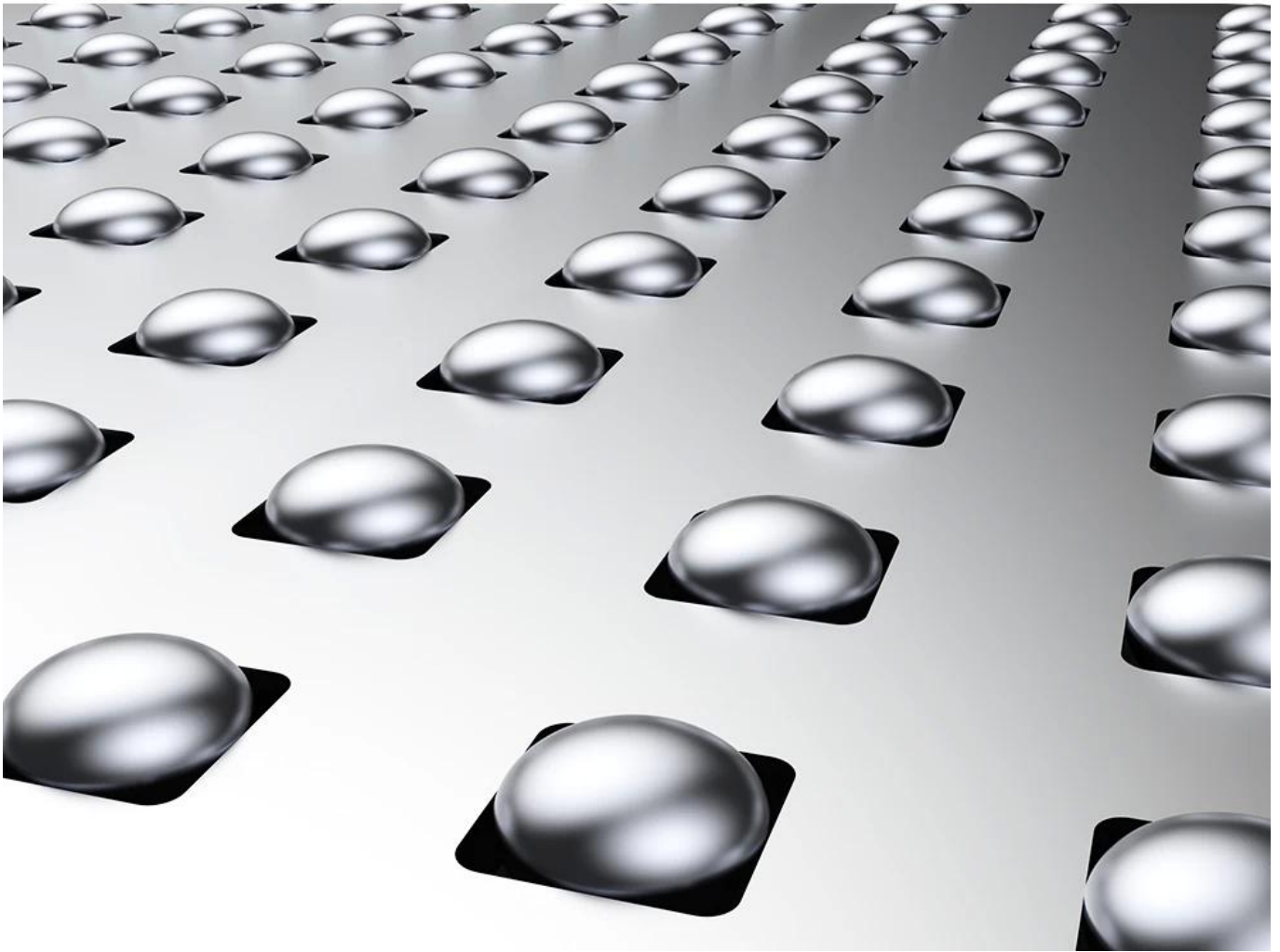


Hard and wear resistant
vertical hole position, no burr



Precision Reballing Stencil

Tin point is neat and tidy



G.W.:25.8G

